

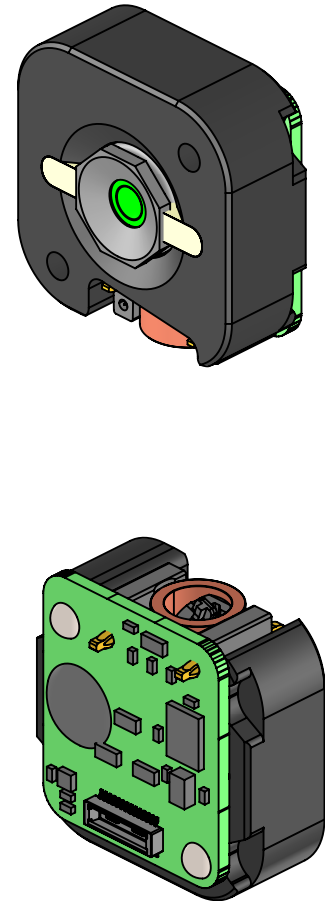
Mosaic Core Specification

Core Number: C302NP		Starter Kit Number: S302NP		Mktg Rev. 3		11/05/2021	
Product Specifications:		Description					
Microbolometer		Uncooled Vanadium Oxide					
Pixel Pitch		12 Microns					
Spectral Response		7.8 - 14 Microns					
Sensor Resolution (Array Format)		320 (h) x 240 (v); 76,800 pixels					
Frame Rate		Slow Frame - <9Hz					
Non-Uniformity Correction (NUC)		Automatic NUC (with shutter)					
Video Output Interfaces		USB					
Power:							
Power Requirement		3.3-5.0V, <50mW (Core only), 300mW (Core + Coprocessor Board)					
Optical & Mechanical:							
Focal Length		2.2mm EFL					
F-number (Focal Length/aperture)		f/1.05					
Spatial Resolution (IFOV, center)		5.23					
Field of View (FOV)		105° Horizontal x 75° Vertical					
Detection Range		186m (based on Johnson Criteria)					
Recognition Range		46m (based on Johnson Criteria)					
Identification Range		27m (based on Johnson Criteria)					
Distance to Spot Ratio		31:1					
Core Size/ Core Weight		10mm x 20mm x 21mm				Core Weight: 8 g	
Seek Software Development Kit:							
Supported Platforms		USB: Seek Linux, Windows, & Android SDK					
Output Formates (User selectable)		Linux / Windows SDK			Android SDK		
		16-bit filtered pre AGC			16-bit filtered pre AGC		
		32-bit ARGB post colorization.			32-bit ARGB post colorization in the bitmap image.		
		32-bit floating point or 16-bit fixed point			32-bit floating point or 16-bit fixed point thermography data.		
Imaging Specifications:		Calibrated Output in °C, °F, K					
Imaging Range		-40°C to +330°C at ambient operating temprature					
Thermography Accuracy		Thermal Image only. No temperature specification					
Sensor Sensitivity		65 mK (typical), <100 mK (max) @ 25°C					
Emmissivity		Factory default emissivity is set to 0.97. Emissivity is adjustable using the SDK.					
Environmental Conditions:							
Operating Temperature Range		-10°C to +60°C (-14°F to 140°F)					
Storage Temperature Range		-40°C to +80°C (-40°F to 176°F)					
Solar Protection		Yes					
Humidity		10%~95%RH, non-condensing					
Regulatory		ROHS, WEEE, REACH					
Accessories:							
Cushion		Yes					
Bracket		Yes					
Sensor Flex		Yes					
Coprocesor Board		Yes					
USB Flex		Yes					
Customer Responsibilities:							
IP Rating		N/A					
Shock/Vibe		Customer responsibility with proper integration into final product housing					

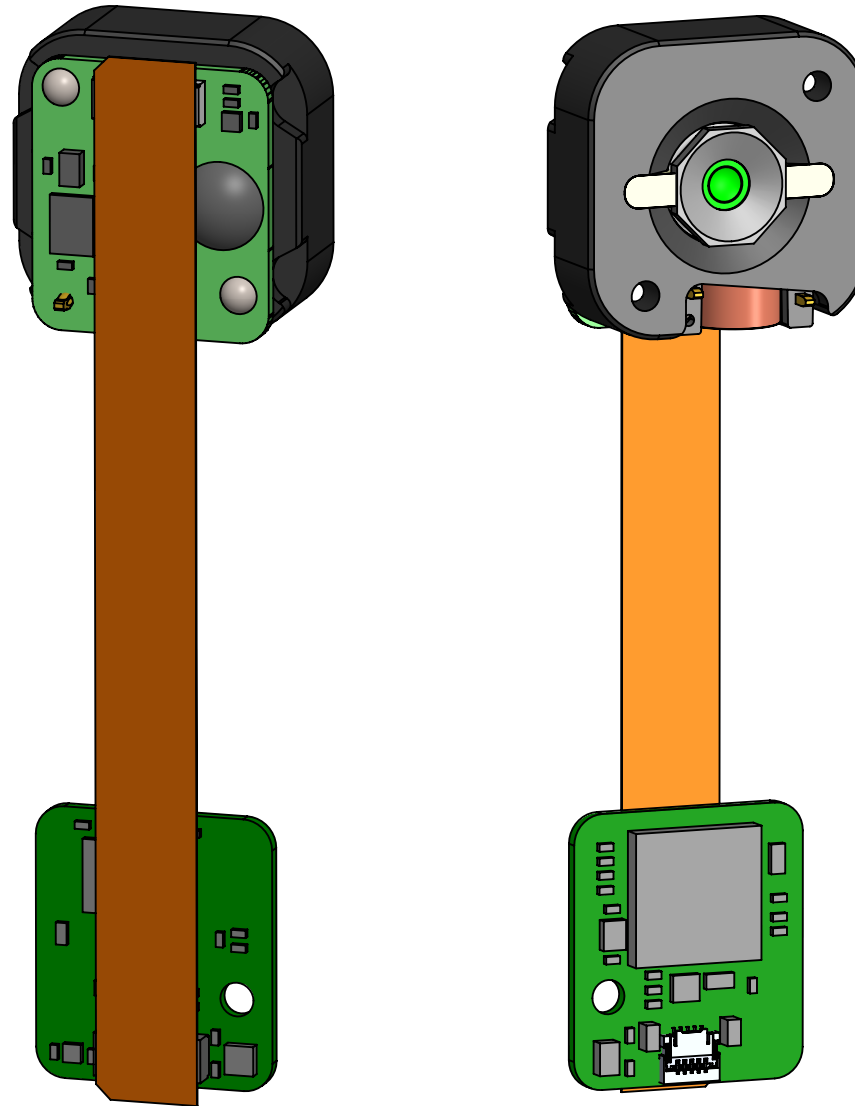
THIS DRAWING COVERS
THE FOLLOWING SKUS:

- C2*2*
- C3*2*
- S2*2*
- S3*2*

NO COPROCESSOR BOARD



"P" OPTION WITH COPROCESSOR BOARD



NOTES:

1. SEE 3D CAD FILE FOR FULL GEOMETRY.
2. KEEPOUT FOR SHUTTER CLEARANCE.
3. LENS ADHESIVE DOES NOT EXTEND ABOVE FRONT FACE.
4. THIS DESIGN IS NOT IPxx RATED.
5. ADHESIVE BUMP PRESENT ON <9Hz CORES.
6. PROCESSOR BOARD AND FLEX INCLUDED WITH "P" OPTION CORES.

MATERIAL	SEE NOTES	DRAWN	DLM	27MAR2019
FINISH	SEE NOTES	APPR.		
UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MM (IN) IN ACCORDANCE WITH ASME Y14.5-2009		THIRD ANGLE PROJECTION		
GENERAL TOLERANCES 0.5 TO 6 ±0.1 [.004] > 6 TO 30 ±0.2 [.008] > 30 TO 120 ±0.2 [.008] > 120 TO 400 ±0.3 [.012] ANGLES ±1°		THE INFORMATION CONTAINED IN THIS DRAWING IS THE SOLE PROPERTY OF SEEK THERMAL. ANY REPRODUCTION IN PART OR AS A WHOLE WITHOUT WRITTEN PERMISSION IS PROHIBITED.		

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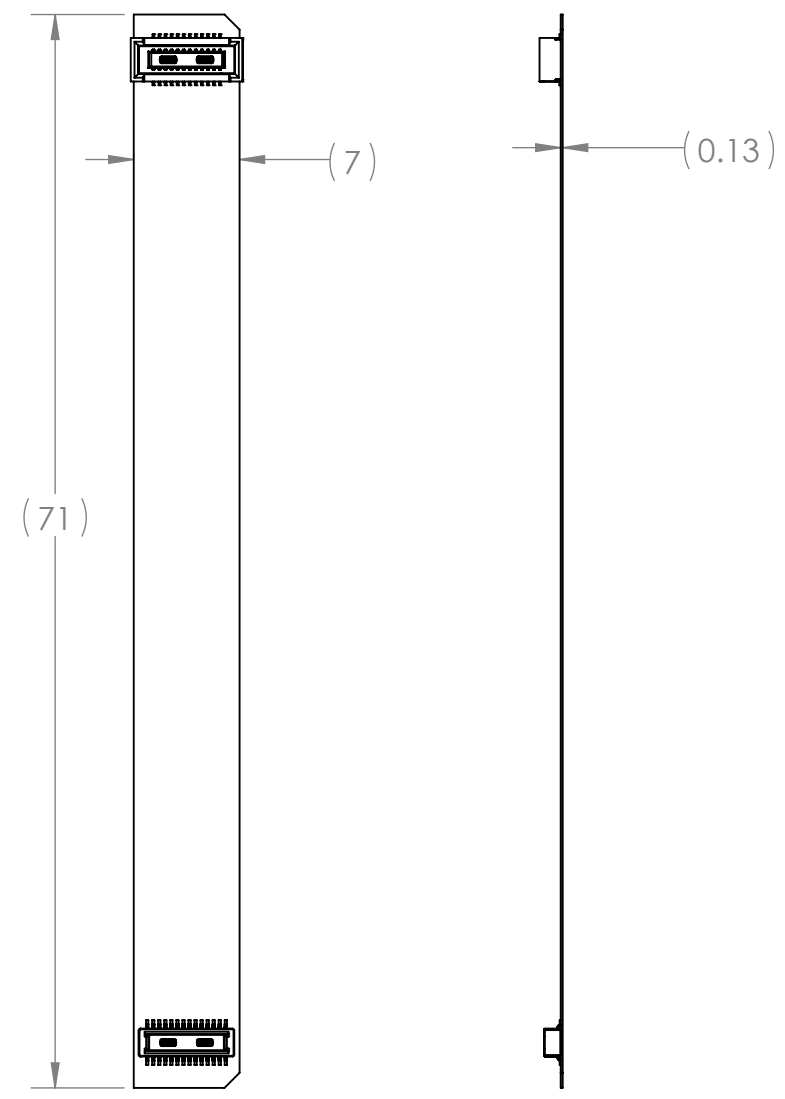
TITLE: DOC, INTERFACE CONTROL
DRAWING, MECH, 2.2MM MOSAIC

SIZE	DWG. NO.	REV
B	DOC_233	4

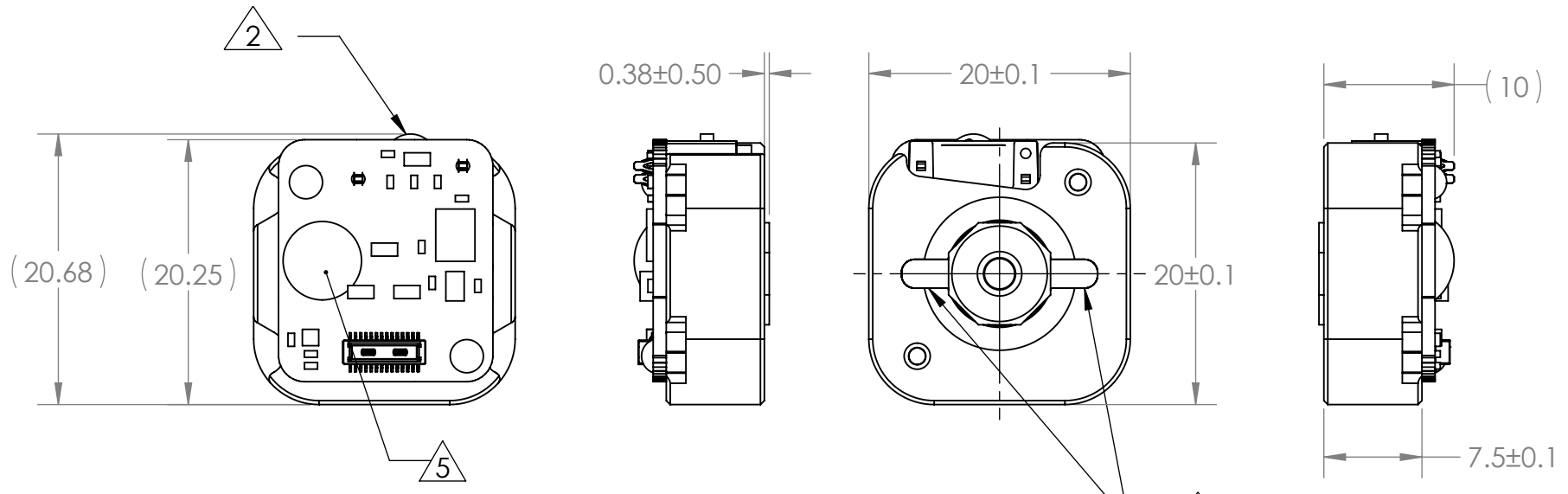
SCALE: 2:1 SHEET 1 OF 2

8 7 6 5 4 3 2 1

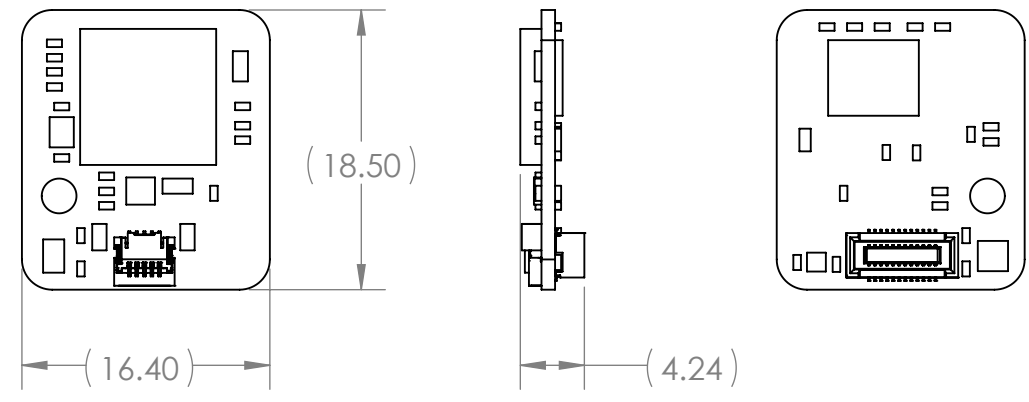
D
C
B
A



FLEX CABLE



THERMAL IMAGING CORE



COPROCESSOR BOARD

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